ASSY. NO.	LED COLOR	(DIFFUSED)
A331. NO.	TOP POSITION	BOTTOM POSITION
571-0101F	BLANK	RED
571-0102F	BLANK	GREEN
571-0103F	BLANK	YELLOW
571-0110F	RED	BLANK
571-0111F	RED	RED
571-0112F	RED	GREEN
571-0113F	RED	YELLOW
571-0120F	GREEN	BLANK
571-0121F	GREEN	RED
571-0122F	GREEN	GREEN
571-0123F	GREEN	YELLOW
571-0130F	YELLOW	BLANK
571-0131F	YELLOW	RED
571-0132F	YELLOW	GREEN
571-0133F	YELLOW	YELLOW

RoHS Compliant 571-01XXF Part Numbers with the "F" suffix ending are RoHS Compliant. Example: 571-0112F Packaging is marked with "RoHS Compliant" label or equivälent markings. Parts can be wave soldered, dip soldered or hand soldered using typical lead-free soldering process with max 260°C temp. for 5 sec.

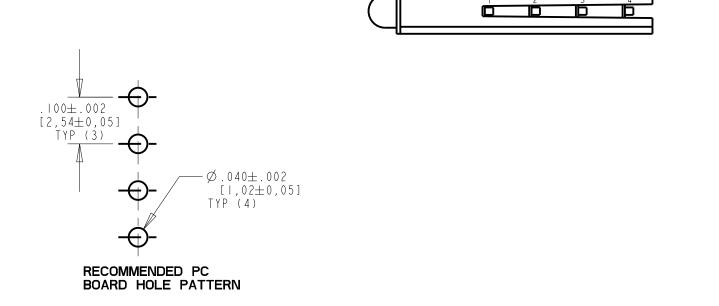
100 [2,54] 100 [2,54] 100 [2,54] 100 [2,54] 100 [2,54] 118±.010 [3±0,25] 118±.010 [3±0,25]	+ + - - - - - - - - - -	.339 150 8,61 3,81]	TOP LED TOP LED O71±.008 [1,8±0,2] BOT. LED CATHODE .020 [0,51] .19
---	--------------------------------	---------------------------	---

OPERA	ATING CHA	RACTERI	STICS A	T 25°C	AMBIENT	
CHARACTERISTICS	COLOR	MIN	TYP	MAX	UNITS	TEST CONDITIONS
	RED	8	15			
LUMINOUS INTENSITY	YELLOW	5	8		mcd	F = 10 mA
	GREEN	5	10		1	
	RED		2.0	2.5		
FORWARD VOLTAGE	YELLOW		2.1	2.5	\ \ \ \	I F = 20 mA
	GREEN		2.2	2.5	1	
	RED		625			
DOMINANT WAVELENGTH	YELLOW		588		nm	
	GREEN		568		1	
	RED		627			
PEAK EMISSION WAVELENGTH	YELLOW		590		nm	
	GREEN		565			
	RED		70		Degree	
VIEWING ANGLE 201/2	YELLOW		70			
	GREEN		70			
	RED		15			
CAPACITANCE	YELLOW		20] pF	V F = 0 V, f = 1 MHz
	CDEEN		1.5			

GKEEN

ABSOLUTE MAXIMUM RATING AT 25°C AMBIENT	RED	YELLOW	GREEN	UNITS
POWER DISSIPATION	105	105	105	mW
FORWARD CURRENT	30	30	25	m A
DERATING LINEAR FROM 25 °C		4 0	. 33	mA/°C
REVERSE VOLTAGE		5		V
LEAD SOLDERING TEMPERATURE, 5 SEC., 1/16" FROM BODY		260		°C
OPERATING TEMPERATURE		- 40 TO +85		°C
STORAGE TEMPERATURE	-40 TO +85			°C

.150 [3,8]

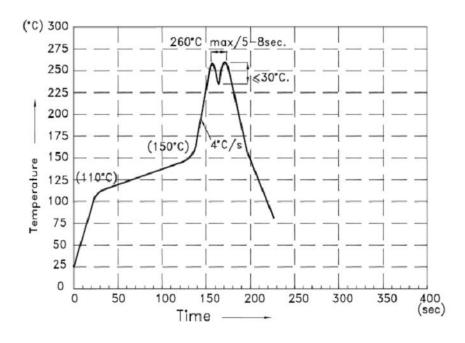


NOTES:

- I. LED LEAD DIMENSIONS ARE MEASURED AT HOUSING EXIT. 2. PIN NUMBERS FOR REFERENCE ONLY, DESIGNATION
- NON-EXISTENT ON PARTS
- 3. DIALIGHT PART NUMBERS: 571-01XXF
- 4. THIS ASSEMBLY CONTAINS ELECTROSTATIC DISCHARGE SENSITIVE DEVICES (ESDS). MAINTAIN ALL PRECAUTIONARY MEASURES DURING
- ASSEMBLY, HANDLING AND STORAGE IN ACCORDANCE WITH IPC-A-610.

 5. RECOMMENDED WAVE SOLDERING TEMPERATURE: 245°C~260°C.
- 6. DO NOT APPLY STRESS TO THE EPOXY RESIN WHEN TEMPERATURE IS ABOVE 85°C.
- 7. SOLDERING PROFILE APPLIES TO LEAD FREE SOLDERING PROCESS (Sn/Cu/Ag ALLOY).
- 8. DURING WAVE SOLDERING, THE PCB TOP SURFACE SHOULD BE KEPT BELOW 105°C.
- 9. DO NOT SOLDER MORE THAN ONCE.

REV	ECN NO	REVISIONS	DRN	CKD	APP	DATE
Α		NEW RELEASE	CE	ΑE	NO	1 - 24 - 08
В		ADDED WAVE SOLDERING PROFILE & NOTES 5,6,7,8,9	AJF	KLJ	NO	9-21-11



RECOMMENDED WAVE SOLDERING PROFILE

